## Coupling Possibilities in LS-DYNA: Development Status and Sample Applications

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### Outline

- Introduction
- Applications
- Conclusion





### Introduction

Park & Felippa: Partitioned analysis of coupled systems. In Belytschko & Hughes (eds.): Computational Methods for Transient Analysis. Amsterdam 1983, pp. 157–219

#### Coupled Problems

- Dynamic Interaction of physically or computationally heterogeneous components
- Interaction is multi-way



Partitioning or splitting of a coupled problem

- Coupled Multi-Field Problems
  - The individual field equations are also functions of the other field
    - Example: velocity and pressure fields for incompressible viscous flow
- Coupled Multi-Physics Problems
  - Multiple physical models or phenomena are handled simultaneously
  - Different discretization techniques are used for individual subproblems
    - Example: particle systems (DEM) interact with structures (FEM) on the same or multiple scales
  - Field variables represent different but interacting physical phenomena
    - Example: thermoelectricity combining heat conduction and electrodynamics





### Classification of the Coupling

- Volume Coupled
  - Discretized field variables (DOF) are coupled on the same domain
  - Weak coupling
    - Thermo-mechanical problem
      displacement & thermal field
  - Strong coupling
    - Incompressible fluid flow
      velocity & pressure field
    - Electro-magnetical problem
      - electric field & magnetic flux density
    - Porous-media problems
      - □ displacement & pressure field
      - displacement, pressure & concentration fields

- Surface Coupled
  - Discretized field variables (DOF) are coupled at an interface surface
  - Weak coupling
    - Mechanical contact
    - Heat transmission
    - Structural sound emission
    - Fluid-structure interaction (low-density fluids)
  - Strong coupling
    - Fluid structure interaction (high-density fluids)





### Solution of Coupled Problems

- Spatial semi discretization
  - Finite-Element Method (FEM)
  - Finite-Difference Method (FDM)
  - Finite-Volume Method (FVM)
  - Arbitrary Lagrange Eulerian (ALE)
  - Boundary-Element Method (BEM)
  - Discrete-Element Method (DEM)
  - Smoothed Particle Hydrodynamics (SPH)
  - Element-Free Galerkin (EFG)
- Time integration
  - Implicit and explicit time-stepping schemes
  - Monolithic or direct approach
    - $\hfill\square$  the problem is treated monolithically
    - □ all components are integrated with the same scheme
  - Partitioned or iterative approach
    - system components are treated as isolated entities
    - separate time integration with arbitrary schemes
    - subcycling to account for different time scales
    - prediction, substitution, and synchronization techniques apply





One-Code Strategy for LS-DYNA

"Combine the multi-physics capabilities into one scalable code for solving highly nonlinear transient problems to enable the solution of coupled multi-physics and multi-stage problems" -- John Hallquist (2012)

- Presented Simulations in the field of
  - Thermo-mechanical coupling
  - Electro-magnetical coupling
  - Fluid-structure interaction
  - Particle-structure interaction



5

## **Thermo-Mechanical Coupling**

Solvers are Connected in a Staggered Solution Scheme

Application: Hot stamping of high strength steel







Thermal Coupling Effects

v ×

Plastic work to heat conversion

$$w_{pl} = \rho c_p \Delta T = \eta \int_{\varepsilon_{pl}} \sigma^{y} d\varepsilon_{pl}$$

Friction-induced heat
 Friction coefficient is very high (0.4 ...0.6)



Note: These are effects of second order in hot stamping





7



Closed contact heat transfer in LS-DYNA







### Subcycling of the Thermo-Mechanical Coupling

The "critical" implicit thermal timestep is usually some orders of magnitude greater than the critical explicit mechanical timestep

$$\Delta t_{therm} \leq \frac{1}{12} \cdot \frac{l^2}{a} \quad ; \quad a = \frac{\lambda}{\rho \cdot c}$$

Model must be able to respond as fast as real life [*Owen* 1993]

- $\lambda$  : thermal conductivity
- c: heat capacity

 $\rho: {\rm density}$ 

$$\Delta t_{mech} \leq \frac{l}{c} \quad ; \quad c = \sqrt{\frac{E}{\rho \left(1 - \nu^2\right)}}$$

**CFL** Condition

*E* : Youngs modulus v : Poisson's ratio  $\rho$  : density



- Example: Steel at room temperature with 1 mm edge length  $\Delta t_{therm} = 7.523 \cdot 10^{-3} \text{ s}$   $\Delta t_{mech} = 1.844 \cdot 10^{-7} \text{ s}$
- Note: Make sure the thermal timestep is small enough to capture the mechanical motion

$$\Delta t_{\text{max}} = \frac{d_{\text{max}}}{v_{\text{max}}}$$
;  $d_{\text{max}} = 1 \dots 5 \text{ mm}$ ;  $v_{\text{max}} = 1 \dots 5 \text{ m/s}$ 







Use of Thermal Contact to Enhance Modeling Skills

- Die surface geometry accurately modeled with shell elements
- Die volume geometry modeled with volume elements
- Shell and volume mesh coupled with contact definition



- Heat transfer from blank to die surface shell by thermal contact
- Heat dissipation into the dies by thermal contact between shell and volume mesh











Cooling Simulation – Is the Coupling Necessary?





Thermo-Mechanical Coupling



#### Coupled Simulation of Forming and Cooling due to Contact with the Die

LS-DYNA KEYWORD DECK BY LS-PRE Time = 17.862 Contours of Temperature min=702.79, at node# 9001295

max=879.144, at node# 9000545







Thermo-Mechanical Coupling



Fringe Levels 8.800e+02

8.600e+02 8.400e+02 8.200e+02 7.800e+02 7.800e+02 7.600e+02 7.400e+02 7.200e+02 7.000e+02 6.800e+02

#### Modeling Phase Transformations

#### \*MAT\_UHS\_STEEL (\*MAT\_244)

 Paul Akerstrom, "Modeling and Simulation of Hot Stamping" Ph.D. Thesis, Lulea University of Technology, 2006

#### Input includes:

- 1. 15 element constituents
- 2. Latent heat
- 3. Expansion coefficients
- 4. Phase hardening curves
- 5. Phase kinetic parameters
- 6. Cowper-Symonds parameters

#### Output includes:

- 1. Austenite phase fraction
- 2. Ferrite phase fraction
- 3. Pearlite phase fraction
- 4. Bainite phase fraction
- 5. Martensite phase fraction
- 6. Vicker's hardness distribution
- 7. Yield stress distribution
- Phase Transformations due to Different Cooling Rates







## **Electro-Magnetical Coupling**

Electro-Magnetic Solver and Connection to Mechanical and Thermal Solvers

Solvers are connected in a staggered solution scheme

	EM Solv	er (SMP & MP)
Ampere's Law:	$\nabla \times \frac{\mathbf{B}}{\mu} = j + \varepsilon \frac{\partial \mathbf{E}}{\partial t}$	$\nabla \times (\cdot)$ : rotation $\nabla \bullet (\cdot)$ : divergence
Faraday's Law:	$\nabla \times \mathbf{E} = -\frac{\partial \mathbf{B}}{\partial t}$	E : electric field B : magnetic flux density
Gauss law: Gauss flux theor	$\nabla \bullet \mathbf{B} = 0$ em: $\nabla \bullet \mathbf{E} = 0$ Equation	j: total current density $j_s$ : source current density
Continuity: Ohm's law:	$\nabla \bullet \mathbf{j} = 0$ $\mathbf{j} = \boldsymbol{\sigma} \mathbf{E} + \mathbf{j}_s$	$\varepsilon, \mu$ , and $\sigma$ : material electrical properties
Displacement	Lorentz forces $\mathbf{F} = \rho_e \mathbf{E} + \mathbf{j} \times \mathbf{B}$	Temperature Joule heating $p = \frac{dQ}{dt} = j^2 R$
Mechanical Sol	Ver Explicit / Implicit	Thermal Solver Implicit (SMP & MPP)
LISTC Livermore Software Technology Corp.		

#### Current EM Status

- All EM solvers work on solid elements for conductors
  - Hexahedrons, tetrahedrons, wedges
- Shells can be used for insulator materials
- Available in both SMP and MPP
- 2D axi-symmetric available
- The EM fields as well as EM force and Joule heating can be visualized in LS-PREPOST :
  - Fringe components
  - Vector fields
  - Element histories
- Only Available in LS-DYNA 980







#### EM Solver Validation

Some T.E.A.M. (Testing Electromagnetic Analysis Methods) test cases have been used to validate LS-DYNA's EM accuracy and to demonstrate its features

T.E.A.M. 28 : An Electrodynamic Levitation Device

- Conducting plate that levitates over two exciting coils
- Plate oscillates and progressively reaches an equilibrium position







max displacement factor=2



#### EM Solver Validation (Cntd.)

 Heating of a steel plate by induction
 In collaboration with: M. Duhovic, Institut für Verbundwerkstoffe, Kaiserslautern, Germany









experiment





Electro-Magnetical Coupling



- Subcycling for the Induced Heating Problem
  - Problem: The coil's current oscillation period is smaller than the total time of the problem
  - Consequence: Many small EM time steps needed
  - Solution: Induced heating solver with "micro" and "macro" time step
  - Application: Conducting plaque moving through coils that induce Joule heating







### EM Applications

- Magnetic Metal Welding
  - Current density fringe



Sheet forming on conical die



 In collaboration with:
 M. Worswick & J. Imbert University of Waterloo, Canada











Forming of a tube-shaft joint



- In collaboration with
  - Fraunhofer Institute for Machine Tools and Forming Technology IWU, Chemnitz Dipl.-Ing. Christian Scheffler
  - Poynting GmbH, Dortmund, Dr Ing, Charlotto Boorwald
    - Dr.-Ing. Charlotte Beerwald







21

### **Fluid-Structure Interaction**

Solver for Incompressible Fluid Dynamics (ICFD)

- Weak and strong coupling to mechanical solver
- Monolithic solution of the thermal fields



#### Current ICFD Status

- Based on a stabilized finite-element formulation
- Stand alone implicit CFD solver with coupling to the
  - Mechanical solver (FSI problems)
  - Thermal solver (Conjugate heat transfer problems)
- ALE approach for mesh movement
- Boundaries of FSI are Lagrangean and deform with the structure
  - Strong coupling available for implicit mechanics (more robust but more costly)
  - Loose coupling for explicit mechanics (less robust and less costly)
- Only Available in LS-DYNA 980







- Automatic Mesh Generation and Refinement
  - Automatic generation of the volume mesh and the boundary layer mesh
  - Possibility to specify local mesh size for better resolution



Error estimators may be used to trigger adaptive re-meshing







#### ICFD Solver Validation

- Flow around a cylinder
  - Re=40: Symmetric flow separation



Re=100: Von Karman Vortex Street









- Mesh used for the simulation
  - Cylinder element size based on a unity Diameter value : 0.01
  - 3 elements added to the Boundary layer
  - 90 0000 elements in total



Comparison of the simulation (red) with experiments (blue)







Level Set Function for Free Surface Problems

Interface is defined by a implicit distance function, i.e., the level set function  $\varphi$ 

- Evolution of  $\varphi$  is computed with a convection equation
- At the interface:  $\varphi = 0$









- Sloshing in a Water Tank
  - Moving Water Tank coming to a brutal halt
  - Sloshing occurs
  - Study of pendulum oscillations







Wave Impact on a Rectangular-Shaped Box:

- Used to predict the force of impact on structure
- The propagation of the wave shape can also be studied
- Will be used and presented as a validation test case in the short term future







#### Source and Sink Problems

- Complex free-surface problems with
  - Source and sink terms
  - Strong FSI coupling
  - Dynamic remeshing
  - Boundary layer mesh









### **Particle-Structure Interaction**

- Definition of the Discrete Elements
  - Particles are approximated with spheres via
    - \*PART, \*SECTION\_SOLID
    - Coordinate using \*NODE and with a NID
    - Radius, Mass, Moment of Inertia

$$M = V \rho = \frac{4}{3} \pi r^3 \rho \qquad I = \frac{2}{5} M r^2 = \frac{8}{15} \pi r^5 \rho$$



Density is taken from \*MAT\_ELASTIC

456+78
TIA RADII
748 5.14
938 4.57
004 3.21
36
Y Z TC RC
6.8 8.7 0 0
4.8 18.2 0 0
4.7 21.2 0 0





Definition of the Contact between Particles

- Mechanical contact
  - Discrete-element formulation according to [Cundall & Strack 1979]



Extension to model cohesion using capillary forces

*CONTROL_DISCRETE_ELEMENT									
\$	-+1	+2	+3		+5	+6	-+7	+8	
\$#	NDAMP	TDAMP	Fric	FricR	NormK	ShearK	CAP	MXNSC	
	0.700	0.400	0.41	0.001	0.01	0.0029	0	0	
\$#	Gamma	CAPVOL	CAPANG						
	26.4	0.66	10.0						

Possible collision states







#### Definition of the Particle-Structure Interaction

- Classical contact: \*CONTACT\_AUTOMATIC\_NODES\_TO\_SURFACE\_ID
  - Well-proven and tested contact definition
  - Benefits of the contact definition
    - static and dynamic friction coefficients
    - □ works great with MPP
  - Drawbacks of the contact definition
    - not possible to apply rolling friction
    - □ friction force is applied to particle center

#### New contact: \*DEFINE\_DE\_TO\_SURFACE\_COUPLING

- Damping determines if the collision is elastic or "plastic"
- Benefits of the contact definition
  - □ static and rolling friction coefficients
  - □ friction force is applied at the perimeter
  - possibility to define transportation belt velocity
- Drawbacks of the contact definition
  - $\hfill\square$  sometimes problems with MPP









#### Funnel Flow

- Variation of the parameters in
  - \*CONTROL\_DISCRETE\_ELEMENT
  - \*DEFINE\_DE\_TO\_SURFACE\_COUPLING

\$+-	1	2-	3	4	l5
RHO	0.80E-6	2.63E-6	2.63E-6	2.63E-6	5 1.0E-6
P-P Fric	0.57	0.57	0.57	0.10	0.00
P-P FricR	0.10	0.10	0.01	0.01	0.00
P-W FricS	0.27	0.30	0.30	0.10	0.01
P-W FricD	0.01	0.01	0.01	0.01	0.00
CAP	0	0	1	1	1
Gamma	0.00	0.00	7.20E-8	2.00E-6	5 7.2E-8
\$+-	1	2	3	4	5





Particle-Structure Interaction



### Drum Mixer

- 12371 particles with two densities
  - Green: foamed clay
  - Blue: sand



#### Hopper Flow

- 17000 particles of the same kind
  - Radii from 1.5 3 mm
  - Static & rolling friction of 0.5







Large Deformations Demand for a Coupled Solution

- Drop of a particle-filled ball from 1m above the rigid ground
  - Inside: 1941 particles (dry sand)
  - Outside: 1.8 mm thick visco-elastic latex membrane









Particle-Structure Interaction



#### Bulk Flow Analysis

Introduction of a particle source and "sink"

#### \*DEFINE\_DE\_INJECTION

- $\hfill\square$  possibility to prescribe
  - location and rectangular size of the source
  - mass flow rate, initial velocity
  - min. and max. radius

#### \*DEFINE\_DE\_ACTIVE\_REGION

definition via bounding box

#### Problem Description

- Belt conveyor
  - Deformable belt
  - Transport velocity
  - Contact with rigid supports
- Generated particles
  - Plastic grains







#### Introduction of \*DEFINE\_DE\_BOND

- All particles are linked to their neighboring particles through Bonds
- Bonds represent the complete mechanical behavior of Solid Mechanics
- Bonds are calculated from the Bulk and Shear Modulus of materials
- Bonds are independent of the DEM
- Every bond is subjected to
  - Stretching, bending
  - Shearing, twisting





The breakage of a bond results in Micro-Damage which is controlled by a prescribed critical fracture energy release rate





### First Benchmark Test with Different Sphere Diameters

- Pre-notched plate under tension
  - Quasi-static loading
  - Material: Duran 50 glass
  - Density: 2235kg/m<sup>3</sup>
  - Young's modulus: 65GPa
  - Poisson ratio: 0.2
  - Fracture energy release rate: 204 J/m<sup>2</sup>
- Case I
  - 4000 spheres r = 0.5 mm
  - Crack growth speed: 2012 m/s
  - Fracture energy: 10.2 mJ
- Case II
  - 16000 spheres r = 0.25 mm
  - Crack growth speed: 2058 m/s
  - Fracture energy: 10.7 mJ
- Case III
  - 64000 spheres r = 0.125 mm
  - Crack growth speed: 2028 m/s
  - Fracture energy: 11.1 mJ











#### Fragmentation Analysis with Bonded Particles





Particle-Structure Interaction



#### Pre-Cracked specimen

- Loading plates via \*CONTACT\_CONSTRAINT\_NODES\_TO\_SURFACE
- Pre-Cracks defined by shell sets

max displacement factor=20







## Conclusion









## Conclusion

Finally, LS-DYNA can boil water!



"Test Drivers" Welcome!

Information on EM solver:

www.lstc.com/applications/em

Information on ICFD solver: www.lstc.com/applications/icfd





# Thank you for your attention!





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